2.0x1.25mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APHBM2012LQBDSURKC

Blue Hyper Red

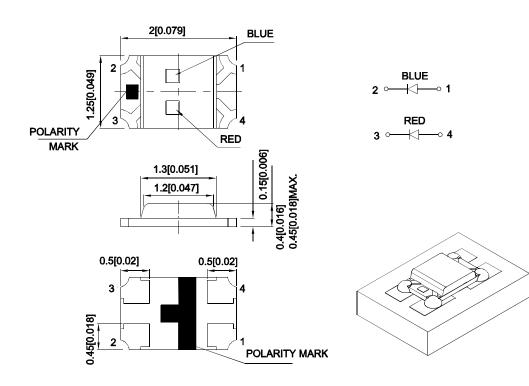
Features

- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Bi -color, low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Blue source color devices are made with InGaN Light Emitting Diode.
- The Hyper Red source color devices are made with Al GaInP on GaAs substrate Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHBM2012LQBDSURKC	Blue (InGaN)	Water Clear	6	12	- 120°
			6*	12*	
	Hyper Red (AlGaInP)		10	20	
			2*	10*	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Min.	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue Hyper Red		460 645		nm	IF=2mA
λD [1]	Dominant Wavelength	Blue Hyper Red		465 630		nm	IF=2mA
Δλ1/2	Spectral Line Half-width	Blue Hyper Red		25 28		nm	IF=2mA
С	Capacitance	Blue Hyper Red		100 35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue Hyper Red	2.2 1.5	2.65 1.75	3 2.1	٧	IF=2mA
lR	Reverse Current	Blue Hyper Red			50 10	uA	VR = 5V

Notes:

- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

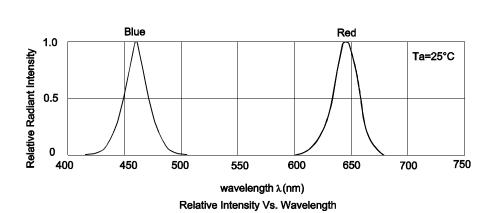
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Hyper Red	Units		
Power dissipation	90	63	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	150	185	mA		
Electrostatic Discharge Threshold (HBM)	250	3000	V		
Reverse Voltage	5		V		
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

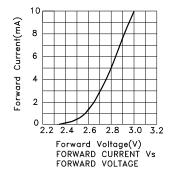
Note:

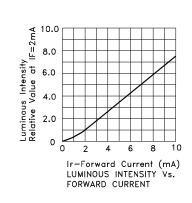
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

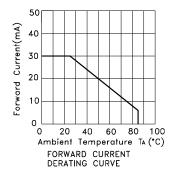
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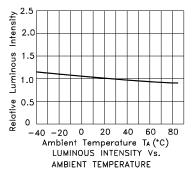


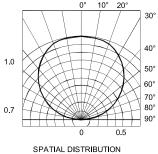
APHBM2012LQBDSURKC Blue







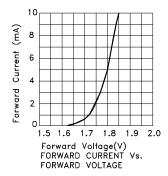


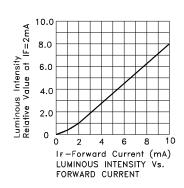


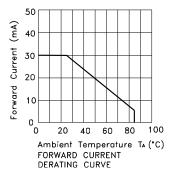
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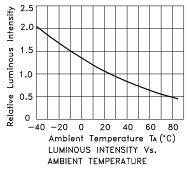
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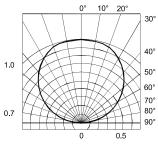
Hyper Red











SPATIAL DISTRIBUTION

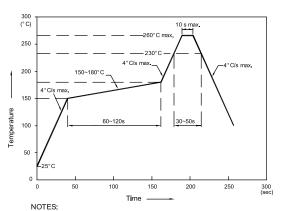
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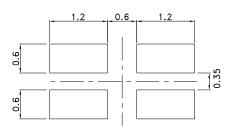
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



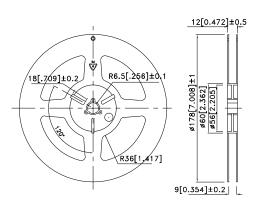
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed $% \left(1\right) =\left(1\right) \left(1\right)$
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

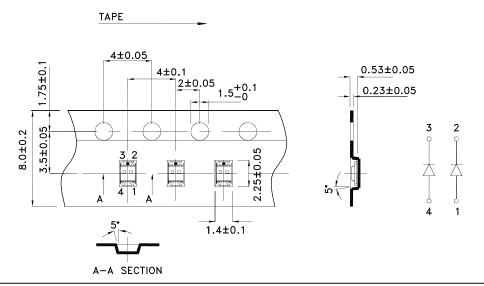
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

Reel Dimension





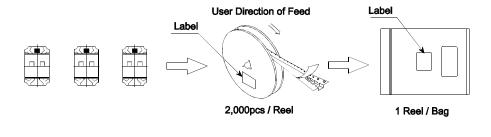
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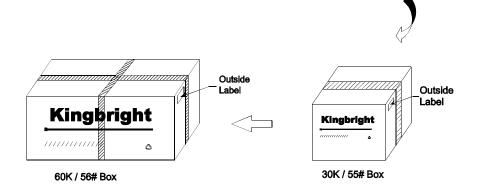
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PACKING & LABEL SPECIFICATIONS

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